

A B C D E

	DIM A	DIM B
B TYPE	11.8	4.8
D TYPE	12.8	5.8

SEE ORDER INFORMATION
SCREW VIEW

1.MATERIAL:

1.1 INSULATOR: PBT+30%GF, UL94V-0.
 INSULATOR COLOR: SEE ORDER INFORMATION.
 1.2 CONTACT: BRASS, FULL GOLD(SEE ORDER INFORMATION)
 PLATED OVER 30u" MIN. NICKEL UNDERPLATED OVERALL.
 1.3 SHELL: STEEL, 50u" MIN, NICKEL PLATED OVERALL.
 1.4 BOARD LOCK: BRASS, 80u" MIN. TIN PLATED OVERALL.
 1.5 RIVET: BRASS, 50u" MIN. NICKEL PLATED OVERALL.
 1.6 SCREW: BRASS, 50u" MIN. NICKEL PLATED OVERALL.

2. ELECTRICAL CHARACTERISTICS:

2.1 CURRENT RATING: 2A
 2.2 CONTACT RESISTANCE: 25mΩ MAX.
 2.3 INSULATION RESISTANCE: 1000MΩ MIN.
 2.4 DIELECTRIC WITHSTANDING VOLTAGE: AC 1000V PER MINUTE.
 2.5 OPERATING TEMPERATURE: -40°C~+105°C.

3. NOTES:

3.1 THIS COMPONENT AND ITS HOMOGENEOUS
 SUBCOMPONENTS ARE RoHS COMPLIANT.
 3.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 5 SECONDS,
 AND ONLY FOR WAVE SOLDERING PROCESS.

4. ORDER INFORMATION:

XDSB-DB32 X DA X 1 FX -09E-T01

INSULATION COLOR:	CONTACT PLATED:	
0: BLACK	F1: GOLD FLASH	F4: 10u" GOLD
4: BLUE (PC99 661C)	F2: 3u" GOLD	F5: 15u" GOLD
	F3: 5u" GOLD	F6: 30u" GOLD

SCREW SPEC.:

1: SEPARATED PACKING 4.8 SCREW
 2: SEPARATED PACKING 5.8 SCREW
 3: NO SCREW
 4: 4.8 SCREW ASSEMBLED
 5: 5.8 SCREW ASSEMBLED

RECOMMENDED PCB LAYOUT(PCB THICKNESS: 1.6mm)
 COMPONENT SIDE VIEW(TOLERANCE: ±0.05)

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REV.	DESCRIPTION	ECN NO.	NAME	DATE
A	NEW RELEASE		Karen	Mar.15.2011

REVISIONS

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15

GENERAL ANGLE:
±3°

TITLE: D-SUB 9P MALE R/A TYPE				
DWG. NO.: C-DB32XDAX1FX-09E			DRAWN: Karen	
PART NO.: XDSB-DB32XDAX1FX-09E-T01			CHECKED: Karen	
UNIT: mm	SCALE: none	SHEET: 1 OF	DWG. SIZE: 1 A4	LAYER: CPC
APPROVED: Frank			RFQ NO.: Q1103140	

XMULTIPLE

ARTICLE: CPC-CN-002-C